

REMARKS

Claims 1-5 and 29 remain pending in the present application. Claim 29 was added via Applicant's response filed May 23, 2002, but does not appear to have been considered by the Examiner. The Examiner is respectfully requested to reconsider and withdraw his rejections in view of the above amendments and remarks as set forth below.

SPECIFICATION

The Examiner has objected to the title of the invention as well as the specification based on certain informalities which do not effect the patentability of the present application. Applicant has amended the specification to correct these informalities. Therefore, Applicant respectfully traverses this rejection.

REJECTION UNDER 35 USC §112

The Examiner has rejected Claim 3 under 35 USC §112, second paragraph, as being indefinite for failing to particularly point out and distinctly claim the subject matter which applicants regard as the invention. In particular, the Examiner states that this claim limitation is not disclosed in the specification. Applicant notes that a basis for this claim language may be found at page 29, lines 21-26 of the specification. Applicant asserts that all pending claims particularly point out and distinctly claim the subject matter of the present invention.

Therefore, reconsideration and withdrawal of this rejection is respectfully requested.

REJECTIONS UNDER 35 USC §103

Claims 1-5 stand rejected under 35 USC §103(a) as being unpatentable over U.S. Patent No. 5,641,714 (Yamanaka). Applicant respectfully traverses this rejection.

Yamanaka is directed generally to a method of manufacturing semiconductor devices. Of particular interest, Yamanaka discloses an adhesive layer 31 and a self-peeling backing material film 33 as shown in Figure 3A. Although Yamanaka appears to teach a technique for reducing the adhesive strength of the adhesive layer, the adhesive strength is uniform over the entire surface thereof. In other words, Yamanaka does not teach or suggest a specific region of the adhesive portion having a less adhesive characteristic than a vicinal region surrounding the specific region.

Applicant's claimed invention is similarly directed to a semiconductor device. However, Claim 1 recites that "the adhesive portion having a specific region having an adhesion smaller than that of a vicinal region of the adhesive portion surrounding the specific region". Therefore, it is respectfully submitted that Claim 1, along with the claims depending therefrom, are patentability distinct over Yamanaka. Accordingly, Applicant respectfully requests reconsideration and withdrawal of this rejection.

Claims 1-5 also stand rejected under 35 USC §103(a) as being unpatentable over U.S. Patent No. 6,429,506 (Fujii). Applicant respectfully traverses this rejection.

In accordance with 35 U.S.C. 103(c), Fujii does not constitute prior art in relation to the present application. Specifically, Fujii does not qualify as a prior art reference under 35 U.S.C. 102(e). Applicant hereby asserts that the subject matter of the present application and Fujii were, at the time the invention was made, under an obligation to be assigned to the same entity, Denso Corporation. Accordingly, Applicant respectfully requests reconsideration and withdrawal of this rejection.

CONCLUSION

All of the stated grounds for rejection have been properly traversed, accommodated, or rendered moot. Applicant therefore respectfully requests that the Examiner reconsider all presently outstanding rejections and further requests that they be withdrawn. Accordingly, it is believed that a full and complete response has been made to the outstanding Office Action and, as such, the present application is in condition for allowance. If the Examiner believes that personal communication will expedite prosecution of this application, he is invited to telephone the undersigned at (248) 641-1230.

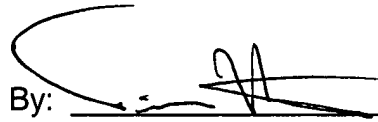
Prompt and favorable consideration of this response is respectfully requested.

Respectfully submitted,

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Harness, Dickey & Pierce, P.L.C.
P.O. Box 828
Bloomfield Hills, MI 48303
(248) 641-1600

TDM/mas

By: 
Timothy D. MacIntyre
Reg. No. 42,824
Attorneys for Applicant

ATTACHMENT FOR SPECIFICATION AMENDMENTS

The following is a marked up version of each replacement paragraph and/or section of the specification in which underlines indicate insertions and brackets indicate deletions.

Please amend the title as follows:

Semiconductor Device Having a [with] Flat Protective Adhesive Sheet
[and Method of Manufacturing the Same]

On Page 7, replace the paragraph on lines 17 through 24 with the following paragraph:

The first adhesive sheet 2 is fixed a flat plate 4 show in FIG. 1B at a side opposite to the adhesive 2b. Specifically, the first adhesive sheet 2 is fixed to the plate 4 by vacuum attraction performed by a vacuum chuck stage (not shown), which is disposed under the plate 4, via a through hole 4a defined in an edge portion of the plate 4. Accordingly, even when the first adhesive sheet 2 is charged, static electricity is removed through the plate 4 having conductivity.